

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) An adhesive composition, comprising:
an insulating resin;
a photopolymerization initiator;
electrically conductive particles; and
an oxetan compound having two oxetane functional groups,
wherein, the oxetan compound is bis((1-ethyl(3-oxetanyl))methyl)ether.
2. (Original) The adhesive composition according to claim 1, comprising 5 to 50 wt% oxetan compound in 100 wt% adhesive composition.
3. (Canceled)
4. (Currently Amended) A connected structure, wherein electrodes on a plastic substrate and on a circuit board that are facing each other are connected by the adhesive composition according to claim 1.
5. (Canceled)
6. (Original) A connected structure, wherein electrodes on a plastic substrate and on a circuit board that are facing each other are connected by the adhesive composition according to claim 2.
- 7-9. (Canceled)